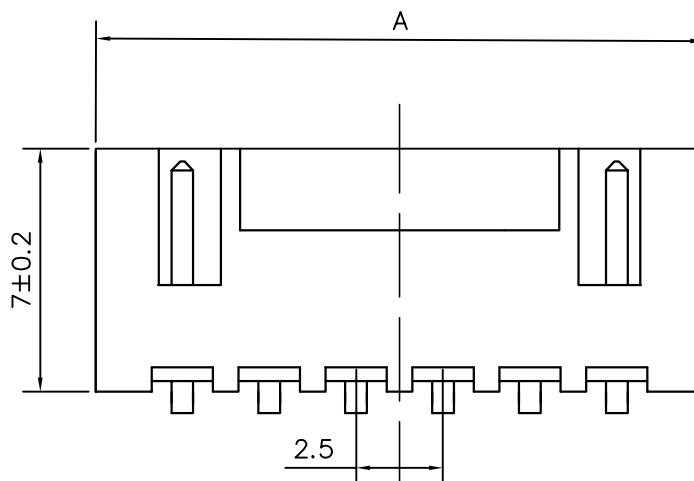
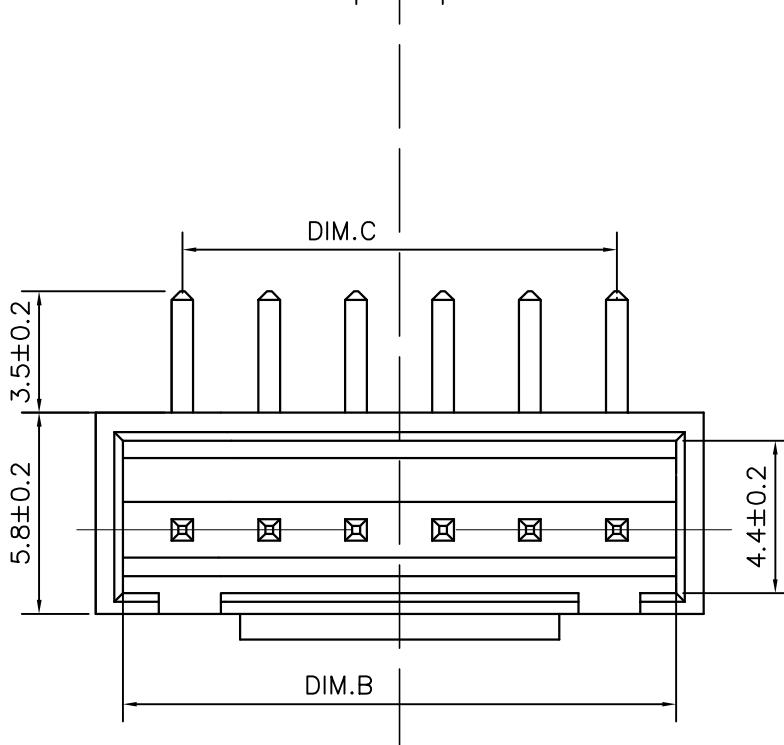


标记 MARK	ECN编号/变更内容 ECN NO/DEFINITION	修改 REVISE	日期 DATE	核准 APPROVE

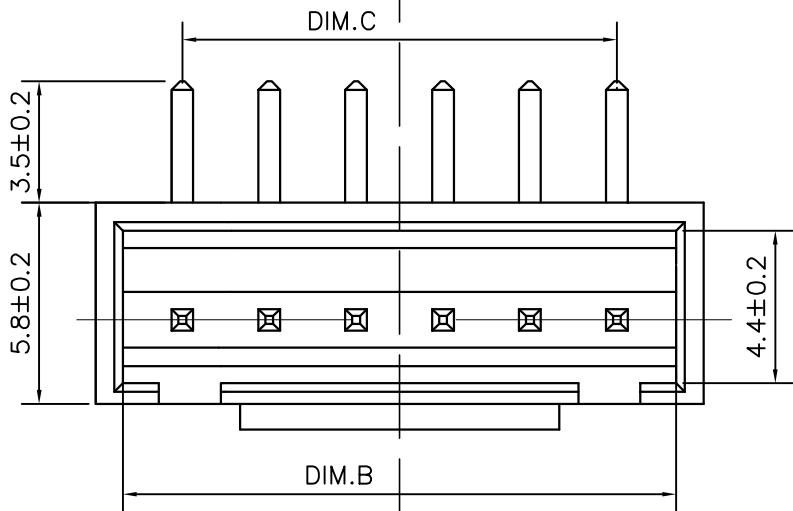
A



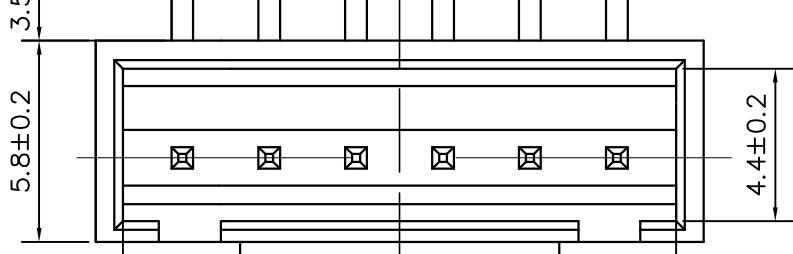
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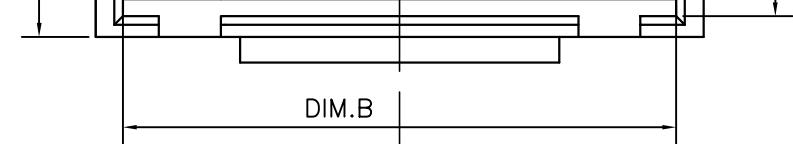
C



D

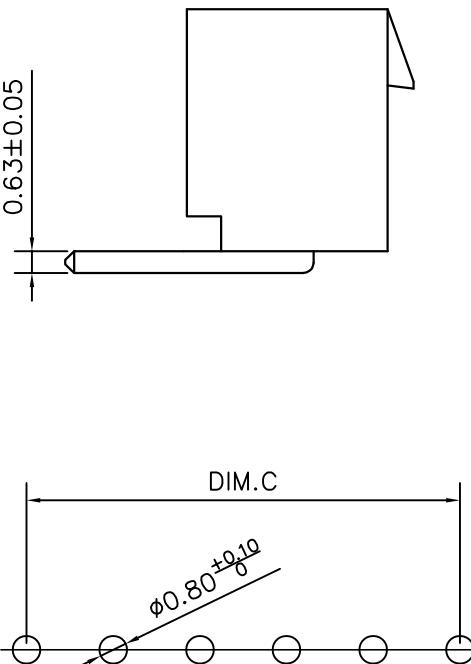
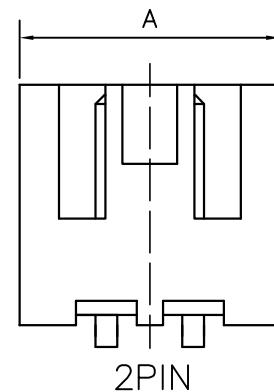


E



F

G



PCB LAYOUT

Pin	DIM A	DIM B	DIM C
2	7.50	6.10	2.50
3	10.00	8.60	5.00
4	12.50	11.10	7.50
5	15.00	13.60	10.00
6	17.50	16.10	12.50
7	20.00	18.60	15.00
8	22.50	21.10	17.50
9	25.00	23.60	20.00
10	27.50	26.10	22.50
11	30.00	28.60	25.00
12	32.50	31.10	27.50
13	35.00	33.60	30.00
14	37.50	36.10	32.50
15	40.00	38.60	35.00

技术要求:

适应基板厚度: $1.2\text{mm} \sim 1.6\text{mm}$
 温度范围: $-25^\circ\text{C} \sim 85^\circ\text{C}$
 额定电压: 250V AC/DC
 额定电流: 3A
 接触电阻: $\leq 0.01\Omega$
 绝缘电阻: $\geq 1000\text{M}\Omega$
 耐压: $1000\text{V AC}/\text{minute}$

2	插针	铜	镀锡	
1	基座	PA66	白色	
序号	品名	材质	电镀/颜色	备注
	品名 TITLE		针座	
	料号 PART NO		HC-XHB-4AW-TW	
	GENERAL TOLERANCES (UNLESS SPECIFIED)	比列 SCALE	1:1	
X.X ±0.35	X: ±3.00°	单位 UNIT	MM	制图 DRAW
X.XX ±0.25	X.X: ±2.00°	张数 PART NO	1 OF 1	审核 CHECKED
X.XXX ±0.15	X.XX: ±1.00°	版本 REV	A	批准 APPROVE
				赵亮亮

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